

EMBEDDED WAFER PREALIGNER

LPA312-1E

Innovative, high-performance, all-in-one design eliminates external controller and interconnecting cables while maintaining drop-in compatibility

Driven by ultra low inertia brushless motors for **smooth, instant response**

Advanced scanning electronics capable of detecting **transparent, semi-transparent and opaque objects** without mechanical repositioning between different wafer sizes

Motion control software featuring a comprehensive set of commonly used commands enabling **compatibility and interface with a variety of semiconductor platforms**

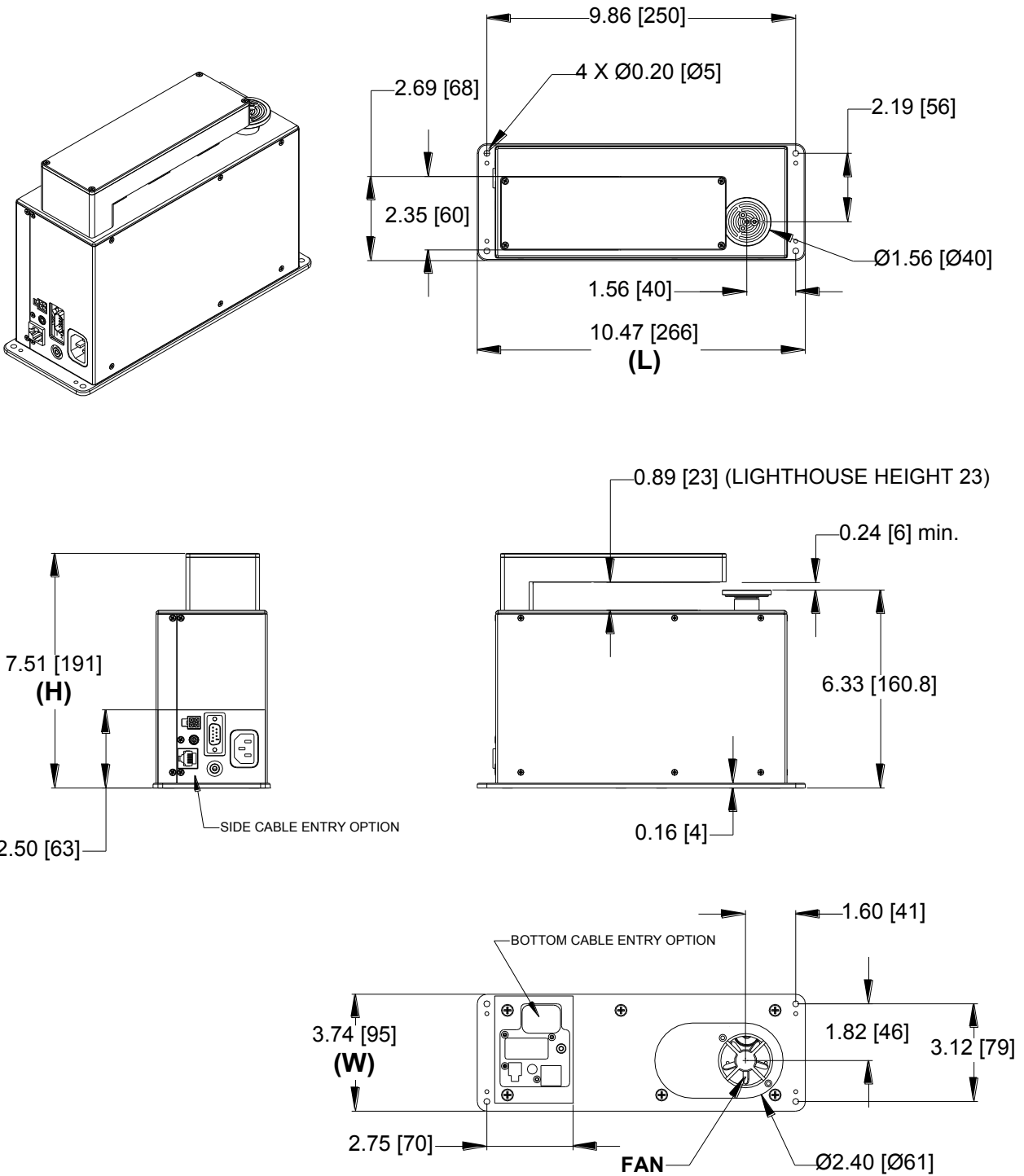
Typical alignment cycle time of less than four seconds facilitates the achievement of **maximum system throughput**



LPA312-1E SPECIFICATIONS

Wafer Diameter		3", 100mm, 125mm, 150mm, 200mm, 300mm
Wafer Opacity		Transparent, Semi-Transparent, Opaque
Square Substrates		Applicable
Wafer Handling		Vacuum Chuck
Centering Accuracy		±50um on the Prealigner Chuck
Angular Accuracy (3 Sigma)	10000 CPR Encoder	±0.06° on the Prealigner Chuck
	24000 CPR Encoder	±0.04° on the Prealigner Chuck
Servo Axes		One
Host Communication		RS232, Ethernet
Max Initial Wafer Offset		10mm
Body Dimensions (W x L x H)		95mm x 266mm x 191mm
Footprint Compatibility		LPA25-1E, LPA38-1E, LPA58-1E, LPA812-1E, LPA1218-1E
Weight		3.50kg
Facilities Required		100-240VAC, 50/60Hz, 48VA, or 24VDC/2A Vacuum 12" Hg
Flat/Notch Compatibility		SEMI Standards Compliant
Cleanliness		Class 1
MTBF		More than 70000 hours

LPA312-1E GENERAL DIMENSIONS



NOTE: All Dimensions — inch [mm]

For model numbers and options download: [LPA Series Prealigners Ordering Guide.pdf](#)